

ABSTRACT

CONNECTION PAD ARRANGEMENTS FOR ELECTRONIC CIRCUIT COMPRISING BOTH FUNCTIONAL LOGIC AND FLASH-EEPROM

An integrated circuit (IC1) comprising functional logic (1) and Flash-EEPROM (2) coupled, via mixing devices (IMUX, OMUX), to connection pads (CP1, CP2), which are arranged into pad arrangements (PAD: PAD1, PAD2, PAD3, PAD4). Each pad arrangement (PAD) comprises two juxtaposed connection pads (CP1, CP2) interconnected electrically and having substantially the same design. In this way, many "probings" are possible on a same pad arrangement, while probing at most two times each connection pad thereof. By probing at most two times on a connection pad, a good "bondability" of the pad is assured. This is particularly useful in the present case of combined functional logic and the Flash-EEPROM where three probings are generally required for the flash test of the EEPROM, the digital test of the functional logical and the analog test of the latter. In a preferred embodiment, the integrated circuit (IC2) comprises a first set of dedicated connection pads (PAD10, PAD11, PAD12) coupled to the functional logic (1), and a distinct second set of dedicated connection pads (PAD21, PAD22) coupled to the Flash-EEPROM (2).

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Fig. 2